

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.03722	0.1	0.401
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01117	0.03	0.1203
	Copper alloy	Iron (Fe)	7439-89-6	0.03722	0.1	0.401
	Copper alloy	Copper (Cu)	7440-50-8	37.13448	99.77	400.0777
<b>Subtotal</b>				<b>37.22009</b>	<b>100</b>	<b>401</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.82019	4.8	30.384
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	5.87539	10.0	63.3
	Filler	Silica fused	60676-86-0	49.94082	85.0	538.05
	Carbon Black	Carbon black	1333-86-4	0.11751	0.2	1.266
<b>Subtotal</b>				<b>58.75391</b>	<b>100</b>	<b>633</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	2.32045	100.0	25
			<b>Subtotal</b>	<b>2.32045</b>	<b>100</b>	<b>25</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01522	2.0	0.164
		Silver (Ag)	7440-22-4	0.01903	2.5	0.205
		Lead (Pb)	7439-92-1	0.72686	95.5	7.831
<b>Subtotal</b>				<b>0.76111</b>	<b>100</b>	<b>8.2</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02368	100.0	0.25513
			<b>Subtotal</b>	<b>0.02368</b>	<b>100</b>	<b>0.25513</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.49194	100.0	5.3
			<b>Subtotal</b>	<b>0.49194</b>	<b>100</b>	<b>5.3</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.42882	100.0	4.62
			<b>Subtotal</b>	<b>0.42882</b>	<b>100</b>	<b>4.62</b>
<b>Total</b>				<b>100</b>	<b>100</b>	<b>1077.37513</b>

#### Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.